LNJ115W89RA

Surface Mounting Chip LED

TSS-2 Type

■ Absolute Maximum Ratings $T_a = 25$ °C

• Yellow Green

Parameter	Symbol	Symbol Rating	
Power dissipation	P_{D}	60	mW
Forward current	I_{F}	20	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V _R	4	V
Operating ambient temperature	T _{opr}	-30 to +85	°C
Storage temperature	T _{stg}	-40 to +100	°C

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

• Soft Orange

Parameter	Symbol	Rating	Unit	
Power dissipation	P _D	55	mW	
Forward current	$I_{\rm F}$	20	mA	
Pulse forward current *	I_{FP}	60	mA	
Reverse voltage	V _R	4	V	
Operating ambient temperature	T _{opr}	-30 to +80	°C ,	
Storage temperature	T _{stg}	-40 to +100	°C	

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics $T_a = 25$ °C

• Yellow Green

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	Io	$I_F = 10 \text{ mA}$	1.8	5.0		mcd
Reverse current	I_R	$V_R = 4 V$			10	μΑ
Forward voltage	V_{F}	$I_F = 10 \text{ mA}$		2.03	2.6	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 10 \text{ mA}$		565		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		30		nm

■ Lighting Color

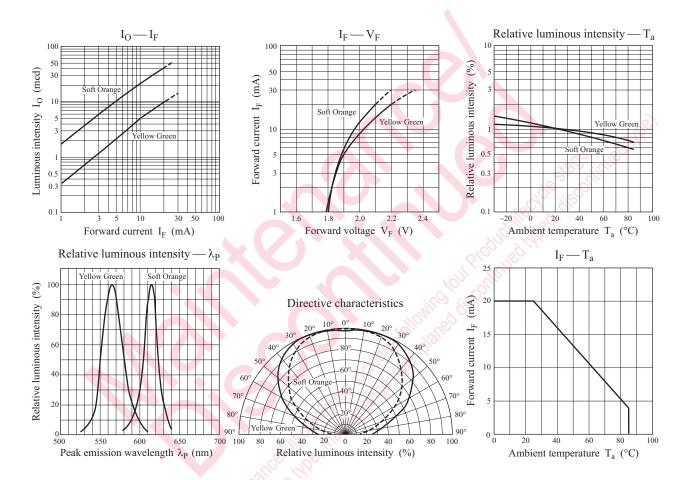
- Yellow Green
- Soft Orange

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■ Electro-Optical Characteristics (Continued) $T_a = 25$ °C

• Soft Orange

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I_{O}	$I_F = 10 \text{ mA}$	7	21		mcd
Reverse current	I_R	$V_R = 4 V$			100	μΑ
Forward voltage	V_{F}	$I_F = 10 \text{ mA}$		1.95	2.5	V
Peak emission wavelength	λ_{P}	$I_F = 10 \text{ mA}$		615		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		20		nm

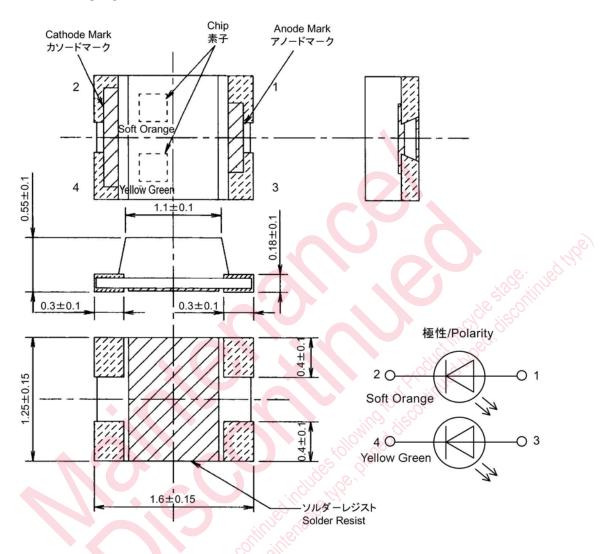


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■ Package (Unit: mm)

KLTFTN4K1540



- Pin name
 - 1, 3: Anode
 - 2, 4: Cathode

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